

Notice of References CitedApplication/Control No.
09/737,397Applicant(s)/Patent Under
Reexamination
TSUCHIYA ET AL.Examiner
Maria GuerreroArt Unit
2822

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	N	WO 00/52230	09-2000	US	Kyle	C23F 11/10
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NON-PATENT DOCUMENTS

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	V	Hayasaki et al. "A new two-step metal-CMP technique for a high performance multilevel interconnects featured by Al and "Cu in low E, organic film" metallizations", 1996, IEEE, pages 88-89.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.